

**Future Innovative Logistics Acceleration Scheme (FILAS)
Under Pilot Subsidy Scheme for Third-party Logistics Service Providers (TPLSP)**

Guidance Note for Third-party Logistics Service Providers (3PLs)

1. Background

- 1.1 Logistics data platforms operated by the Government or public organisations, including Port Community System (PCS) and Hong Kong International Airport Cargo Data Platform (HKIA Cargo), have been commissioned. To support the upgrading and transformation of the maritime and logistics sectors, these platforms adopt advanced technologies such as Artificial Intelligence (AI), big data and blockchain, to enhance operational efficiency, transparency and connectivity across the logistics chain.
- 1.2 To unleash the full potential of the logistics data platforms in promoting digitalisation of the logistics industry, it is essential to ensure the provision of logistics data platform onboarding IT solutions in the market so as to help logistics small and medium enterprises (SMEs) to adopt the platforms concerned.
- 1.3 To this end, as announced in the 2026-27 Budget, FILAS was launched on 1 June 2026 a sub-scheme under the Pilot Subsidy Scheme to subsidise 3PLs (in particular SMEs) to subscribe or use logistics data platform IT onboarding solutions, so as to elevate the level of digitalisation among 3PLs and boost the rate of adoption of designated logistics data platforms operated by the Government or public organisations, including the PCS and HKIA Cargo, with knock-on benefits to Hong Kong's maritime, trading and financial sectors.

White List of Pre-approved Solutions

- 1.4 To expedite the procurement of the onboarding solution for the specified logistics data platform(s), a white list mechanism was introduced under FILAS to select pre-approved solutions that are considered compliant with all the specifications set by the operators of the specified platform(s) and are capable of supporting digitalisation of the end-to-end operations of 3PLs for the use of logistics enterprises. As a start, three selected solutions are included in the white list (**Annex**). The list will be updated to include new selected solutions at around half-yearly intervals.

2. Scope of the Scheme

- 2.1 FILAS supports the one-off purchase and/or subscription of pre-approved IT onboarding solutions on the white list by 3PLs. Eligible 3PLs may now apply for a subsidy under FILAS for subscribing to or using the listed solutions.

3. Eligibility, Application, Assessment and Vetting

- 3.1 All non-listed enterprises¹ registered in Hong Kong under the Business Registration Ordinance (Cap. 310) with substantive business operations in providing third-party logistics services in Hong Kong are eligible to apply.
- 3.2 In line with the Government's policy objective to promote Hong Kong as an international logistics hub, the business of applicant enterprises should be related to either inbound or outbound goods, rather than goods purely for domestic consumption.
- 3.2 An applicant enterprise must provide documentary evidence proving its substantive business operations in providing third-party logistics services in Hong Kong at the time of application. Factors that will be taken into account in assessing the eligibility of applicant enterprises with respect to this eligibility requirement and examples of the documents that may serve as the relevant proof are at **Annex 2** in Guide to Application for the TPLSP.
- 3.3 To apply for FILAS, applicant enterprises should complete and submit the electronic application form together with electronic copies of the required supporting documents set out in paragraph 3.1.4 in Guide to Application for the TPLSP. FILAS is open for application all year round.
- 3.4 The completed application form together with copies of the required supporting documents set out in paragraph 3.1.4 should be submitted to the Secretariat via email (tplsp_sec@hkpc.org). Submission of application by post or other means not prescribed above will not be accepted.
- 3.5 Please refer to paragraphs 2.1, 3 and 4 of the Guide to Application for the TPLSP for details on the eligibility requirements, application procedures, assessment criteria and vetting arrangements.

4. Funding Support and Reporting Requirement

- 4.1 The total cumulative subsidy ceiling per applicant enterprise under the TPLSP (including FILAS) is HK\$2 million (including audit fee of project). The Government will cover a maximum of two-thirds of the total approved project cost and the applicant enterprise has to contribute no less than one-third of the total approved project cost in its own cash (except the audit fee of project), excluding any fundings and/or sponsorships from other non-Government sources on that particular approved project.
- 4.2 Funding approved under FILAS will be disbursed in three instalments:

¹ Subsidiaries of listed enterprises if they themselves are not listed are also eligible. On the other hand, all listed enterprises, their subsidiaries which are listed or those planning to be listed in the coming year are not eligible.

Payment	Percentage of Approved Funding	Condition for Disbursement
Initial payment	30%	Upon approval of the application and signing of the funding agreement
Interim payment	20%	Upon submission of the project progress summary for the first six months, subject to endorsement by the Management Committee of TPLSP (MC)
Final payment	50%	Upon completion of the project and submission of the final and audited reports, subject to endorsement by the MC

4.3 Each approved project should be completed within 24 months.

4.4 To facilitate the monitoring and evaluation of approved projects, applicant enterprises must submit the required documents to the Secretariat for review as follows:

Project Duration	Project Progress Summary	Submission of Final Reports and Final Audited Accounts
6 months or below	Not required	Within two months upon project completion
More than 6 months and up to 24 months	Submission of a payment disbursement form with project progress summary and financial position for the first 6 th month period within two weeks after the end of the 6 th month	Within two months upon project completion

4.5 Please refer to paragraphs 1.4, 5.1-5.5 and 6 of the Guide to Application for the TPLSP for details on the funding principles, disbursement arrangement and reporting requirement.

4.6 The funding facility of FILAS is \$30 million. Applications are processed on a first-come-first-served basis. However, funding allocation in respect of applications depends on whether a given application is complete, i.e. whether all documents as required by the Secretariat are received and to the satisfaction of the Secretariat. In case of near depletion of funding under FILAS, the last tranche of funding will be awarded to whichever application under processing that meets the above completion condition first, irrespective of the sequence in which those applications still under processing were received.

5. Procurement Procedure

- 5.1 For a FILAS project involving the subscription to or procurement of a pre-approved solution on the white list, applicant enterprises are **not** required to comply with the procurement requirement under paragraph 5.6 of the Guide to Application for the TPLSP. Applicant enterprises must, however, obtain **one written quotation** from the solution provider of the selected pre-approved solution, irrespective of the aggregate procurement value.
- 5.2 The solution provider of a pre-approved solution on the white list is also **not** required to meet the solution provider eligibility requirement under paragraph 2.2 of the Guide to Application for the TPLSP.
- 5.3 For other procurement-related requirements, including avoidance of conflict of interest, risk and title to equipment and return of residual funds, please refer to paragraphs 5.7–5.9 of the Guide to Application for the TPLSP.

6. Administrative and Contractual Requirements

Please refer to paragraph 7 of the Guide to Application for the TPLSP for details of the administrative and contractual requirements.

7. Enquiries

Enquiries regarding FILAS can be addressed to HKPC, the Secretariat of the TPLSP:

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Kowloon, Hong Kong
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**Secretariat of the Pilot Subsidy Scheme for Third-Party Logistics Service Providers
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